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TABLE OF CONTENTS

Face-Down and Heterogeneous Chip Bonding Technology on Waffle-Wafer for Bumpless Chip-An-Wafer (COW) Package	1
<i>Yoshiaki Satake, Tatsuya Funaki, Wataru Doi, Hajime Kato, Shogo Okita, Takayuki Ohba</i>	
Advanced Development of Squeeze Effect Non-Contact Handling Tool for Semiconductor Chips	4
<i>Hayato Hishinuma, Masaaki Miyatake, Hiroshi Kikuchi, Yuta Tobari</i>	
Towards 3D AI Hardware: Fine-Grain Hardware Characterization of 3D Stacks for Heterogeneous System Integration & AI Systems	8
<i>Eren Kurshan, Paul D. Franzon</i>	
Impact of 2-Dimensional Materials for 3D Power IC	14
<i>Ayano Furue, Mastaka Hasegawa, Satoshi Matsumoto</i>	
Detectability of Resistive Open Defects with Analog Relaxation Oscillators Under Unit-To-Unit Variations of Dies	19
<i>Yuya Yamahashi, Yuto Ohtera, Hiroyuki Yotsuyanagi, Shyue-Kung Lu, Masaki Hashizume</i>	
3D Stacked Spin Qubit by TCAD Simulations	24
<i>Tetsufumi Tanamoto</i>	
A Novel Direct Transfer Bonding Process with Particle Less Tapes for Die to Wafer Integration.....	28
<i>Tomoka Kirihata, Masanori Yamagishi, Ichiro Sano, Haruka Morita, Yusuke Fumita, Shinya Takyu</i>	
Antioxidative Cu Electrodeposition for 3D Interconnects with Hybrid Bonding.....	33
<i>Ryo Aizawa, Masahiro Sawa, Jinta Nampo, Yurina Fukumoto, Murugesan Mariappan, Takafumi Fukushima</i>	
Process Development for a Novel Low Loss and Non-PFAS Photo Imageable Dielectric for RF Silicon Interposer Applications	37
<i>Hamideh Jafarpoorchekab, Xiao Sun, Angel Uruena, Siddhartha Sinha, Nelson Pinho, Andy Miller, Nadine Collaert</i>	
Clean Dicing: An Alternative Blade Dicing Technique for Minimising Particles in 3D Heterogeneous Integration.....	43
<i>Akito Hiro, Damien Jon Leech, Geert Schoofs, John Slabbekoorn, Alain Phommahaxay, Koen Kennes, Gerald Beyer, Eric Beyne</i>	
Direct Sputtered Copper Seed Layer Formation on Low Dielectric Resin to Reduce Transmission Loss	48
<i>Akihiro Shimizu, Kazuhiro Fukada, Shinichi Endo, Mitsuru Abe, Akiko Matsui</i>	
16-Layer 3D Stacking Based on Self-Assembly Technology for HBM Application.....	52
<i>Du Zehua, Hiroshi Kikuchi, Hayato Hishinuma, Tetsu Tanaka, Takafumi Fukushima</i>	
Ultra-High Density Deep Trench Capacitor (DTC) for 3DIC Integration.....	55
<i>H. L. Cheng, J. Y. Lin, T. C. Hsu, Eva Su, S. M. Wu, Y. C. Chang, T. H. Chien, C. Y. Peng, J. H. Yang, Felix Tsui, S. F. Huang</i>	
A Temporary Bonding De-Bonding Tape with High Thermal Resistance, Easy Peeling and Excellent TTV for 3DIC.....	58
<i>Moeki Nakano, Shigenori Nagahama, Toshio Takahashi, Takuya Yamamoto</i>	

Die-To-Wafer Hybrid Bonding Impact at MM-Wave Frequencies	61
<i>Mohammad Alsukour, Olivier Valorge, Margot Faure, Loïc Vincent, Victor Milon, Pascal Chevalier, Emmanuel Pistono, Jean-Daniel Arnould, Christophe Dubarry</i>	
Characterization of Ozone-Ethylene Radical Pretreatment for Hybrid Bonding Without Water Rinsing Processes	67
<i>Bungo Tanaka, Tatsunori Shino, Mariappan Murugesan, Tetsu Tanaka, Takafumi Fukushima Niche</i>	
Cost-Effective Low-Temperature Hybrid Bonding Using Layer Transfer Technology	71
<i>Yu-Lun Liu, Chun-Ta Li, Tzu-Han Sun, Chien-Kang Hsiung, Yuan-Chiu Huang, Kuan-Neng Chen</i>	
Low-Temperature Adhesive Hybrid Bonding Technology with Novel Area-Selective Passivation Layer.....	75
<i>Tzu-Han Sun, Yu-Lun Liu, Chun-Ta Li, Wen-Tzu Tsai, Mu-Ping Hsu, Kuan-Neng Chen</i>	
Machine Learning-Based Diagnosis of Defects in Chiplet Interconnects	79
<i>Junming Li, Huaguo Liang, Xianrui Dou, Le Yu, Zhengfeng Huang, Yingchun Lu, Cuiyun Jiang</i>	
Gate Driver IC for GaN Power Device Suitable for 3D Power IC	85
<i>Yusuke Ohgushi, Satoshi Matsumoto</i>	
Surface Modification for Ultrasonic Cu-To-Cu Direct Bonding	89
<i>Chih-Hsien Chiu, Wei-Ting Chen, Jenn-Ming Song</i>	
3D SRAM Design & Optimization with Open Source Memory Compiler	93
<i>Sunan Chen, Chao Wu, Yunlang Cai, Yuan Guan, Yuanqing Cheng</i>	
Thermal Analysis of Reflow Process for PIC-Embedded Package Substrate with 2.3D RDL Interposer for Co-Packaged Optics.....	98
<i>Akihiro Noriki, Hirotaka Uemura, Haruhiko Kuwatsuka, Naoki Matsui, Reona Motoji, Dan Maeda, Tomoya Sugita, Fumi Nakamura, Takeru Amano</i>	
Creep Behavior of Low-Temperature Sn-In Solder Using Nanoindentation Test	101
<i>Shunya Nitta, Hiroaki Tatsumi, Hiroshi Nishikawa</i>	
Impact of Cu Pad Density on Cu-CMP and Bonding Yield for Chip-To-Wafer Hybrid Bonding	104
<i>Murugesan Mariappan, Hiroyuki Hashimoto, Kentaro Mihara, Takashi Hare, Takafumi Fukushima, Fumihiro Inoue, Akira Uedono</i>	
Temporary Adhesive Effect on Multichip Thinning for Rapid Prototyping of 3D-IC from 2D-IC Fabricated in Foundry Shuttle Services	109
<i>Akihiro Tominaga, Jiayi Shen, Chang Liu, Atsushi Shinoda, Tetsu Tanaka, Takafumi Fukushima</i>	
TSV Formation Using a Direct CU Electroplating on Electroless Plated Barrier Layer with a Low Resistivity	112
<i>Yuko Ishii, Takanobu Hamamura, Tomohiro Shimizu, Takeshi Ito, Shoso Shingubara</i>	
Room-Temperature and Compressive Force-Free Metal-Metal Direct Bonding for Heterogeneous Integration of Micro-LED Array on 3D-IC	115
<i>Jiayi Shen, Chang Liu, Tetsu Tanaka, Takafumi Fukushima</i>	

A Novel Multi-Chip Cooling System Using Direct-On-Chip Jet Impingement for High-Performance Interposer Package	118
<i>Akshat Hetal Patel, Ketan Yogi, Gopinath Sahu, Tiwei Wei</i>	
Supression of TSV-Induced Stress by Using Negative Thermal Expansion Material	124
<i>Hisashi Kino, Takafumi Fukushima, Tetsu Tanaka</i>	
Thermal Flow Simuation and Measurements of 3D Si Chip Stacks with TSVs.....	127
<i>Shuhei Yokota, Rikuu Hasegawa, Kazuki Monta, Takaaki Okidono, Takuji Miki, Makoto Nagata</i>	
Electrochemical Deposition of Indium for Scalable 3D Quantum Chiplets	130
<i>Jowesh Avisheik Goundar, La Thi Ngoc Mai, Moris Yuki, Otake Yugi, Hideo Kosaka, Fumihiro Inoue</i>	
Plasma Hydrophilic Treatment for Improved Wafer Bonding Strength Via Polysilazane	134
<i>Nemoto Daiki, Kai Takeuchi, Eiji Higurashi</i>	
Activation of Copper Surfaces by VUV - Redox Method Using a Xenon Excimer Lamp.....	137
<i>Shinichi Endo, Akihiro Shimizu</i>	
Superconducting Titanium Nitride in Through-Silicon Vias for 3D Integration of Qubits	140
<i>Alexandra Schewski, Ulrich Schaber, Armin Klumpp</i>	

Author Index